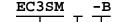
EC3SM-B-20-32.000M





Series 4.0mm Epoxy Base SMD Crystal

Frequency Tolerance/Stability ±50ppm at 25°C, ±100ppm over 0°C to +70°C

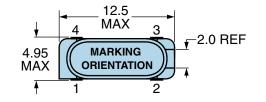
Mode of Operation -BT-Cut Fundamental

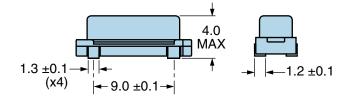
ELECTRICAL SPECIFICATIONS	

Nominal Frequency	32.000MHz
Frequency Tolerance/Stability	±50ppm at 25°C, ±100ppm over 0°C to +70°C
Aging at 25°C	±5ppm/year Maximum
Load Capacitance	20pF Parallel Resonant
Shunt Capacitance (C0)	7pF Maximum
Equivalent Series Resistance	40 Ohms Maximum
Mode of Operation	BT-Cut Fundamental
Drive Level	1mWatts Maximum
Storage Temperature Range	-40°C to +85°C
Insulation Resistance	500 Megaohms Minimum at 100Vdc

ENVIRONMENTAL & MECHANICAL SPECIFICATIONS		
Fine Leak Test	MIL-STD-883, Method 1014 Condition A	
Gross Leak Test	MIL-STD-883, Method 1014 Condition C	
Mechanical Shock	MIL-STD-202, Method 213 Condition C	
Resistance to Soldering Heat	MIL-STD-202, Method 210	
Resistance to Solvents	MIL-STD-202, Method 215	
Solderability	MIL-STD-883, Method 2003	
Temperature Cycling	MIL-STD-883, Method 1010	
Vibration	MIL-STD-883, Method 2007 Condition A	

MECHANICAL DIMENSIONS (all dimensions in millimeters)





PIN	CONNECTION	
1	Crystal	
2	Connected to Pin 3	
3	Connected to Pin 2	
4	Crystal	
LINE MARKING		
1	E32.000 E=Ecliptek Designator	

ICAL SPECIFICATIONS		
quency	32.000MHz	
olerance/Stability	±50ppm at 25°C, ±100ppm over 0°C to +70°C	
C	±5ppm/year Maximum	
tance	20pF Parallel Resonant	
itance (C0)	7pF Maximum	
eries Resistance	40 Ohms Maximum	
ration	BT-Cut Fundamental	
	1mWatts Maximum	

-20 -32.000M

Load Capacitance 20pF Parallel Resonant

Nominal Frequency

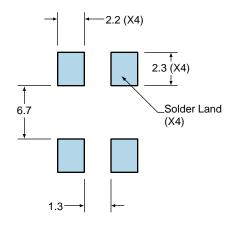
32.000MHz

EC3SM-B-20-32.000M



Suggested Solder Pad Layout

All Dimensions in Millimeters

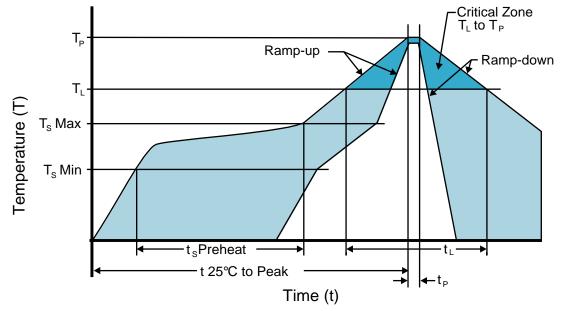


All Tolerances are ±0.1



Recommended Solder Reflow Methods

EC3SM-B-20-32.000M



Low Temperature Infrared/Convection 225°C

T _s MAX to T _L (Ramp-up Rate)	5°C/second Maximum
Preheat	
- Temperature Minimum (T _s MIN)	N/A
- Temperature Typical (T _s TYP)	150°C
- Temperature Maximum (T _s MAX)	N/A
- Time (t _s MIN)	30 - 60 Seconds
Ramp-up Rate (T _L to T _P)	5°C/second Maximum
Time Maintained Above:	
- Temperature (T∟)	150°C
- Time (t∟)	200 Seconds Maximum
Peak Temperature (T _P)	225°C Maximum
Target Peak Temperature (T _P Target)	225°C Maximum 2 Times
Time within 5°C of actual peak (t _p)	80 seconds Maximum 2 Times
Ramp-down Rate	5°C/second Maximum
Time 25°C to Peak Temperature (t)	N/A
Moisture Sensitivity Level	Level 1

Low Temperature Manual Soldering

185°C Maximum for 10 seconds Maximum, 2 times Maximum.

High Temperature Manual Soldering

260°C Maximum for 5 seconds Maximum, 2 times Maximum.